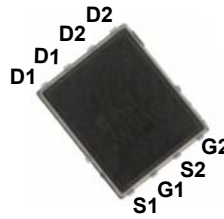
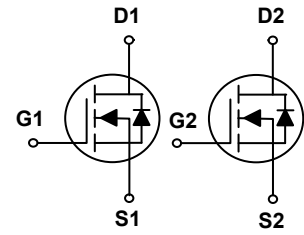


Main Product Characteristics

$V_{(BR)DSS}$	500V
$R_{DS(ON)}$	3.6Ω
I_D	3A



PPAK5x6



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSFP03N50T utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	500	V
Gate-Source Voltage	V_{GS}	±30	V
Drain Current – Continuous ($T_c=25^\circ\text{C}$)	I_D	3	A
Drain Current – Continuous ($T_c=100^\circ\text{C}$)		1.9	A
Drain Current – Pulsed ¹	I_{DM}	15	A
Single Pulse Avalanche Energy ²	E_{AS}	13	mJ
Single Pulse Avalanche Current ²	I_{AS}	5	A
Power Dissipation ($T_c=25^\circ\text{C}$)	P_D	63	W
Power Dissipation – Derate above 25°C		0.5	W/ $^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	62	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction to Case	$R_{\theta JC}$	---	2	$^\circ\text{C}/\text{W}$

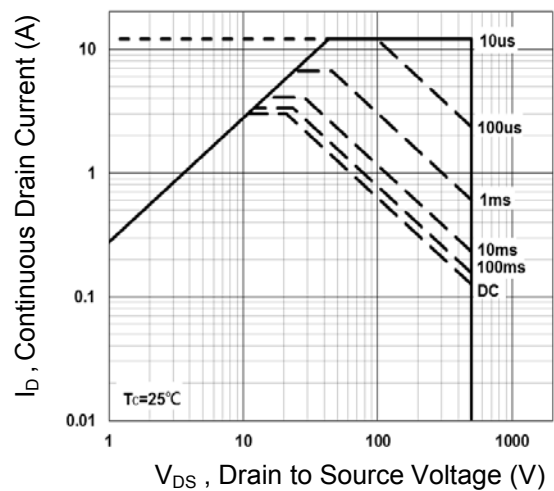
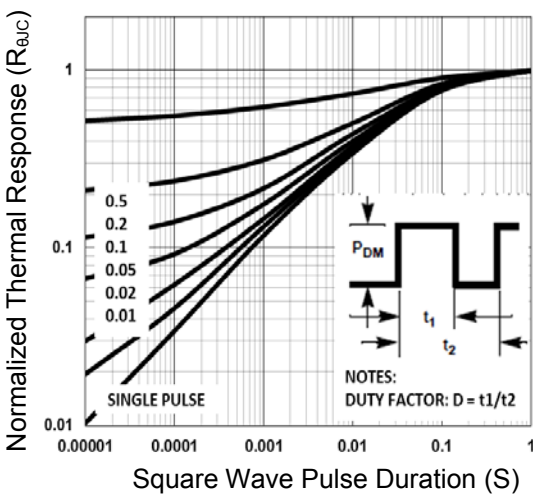
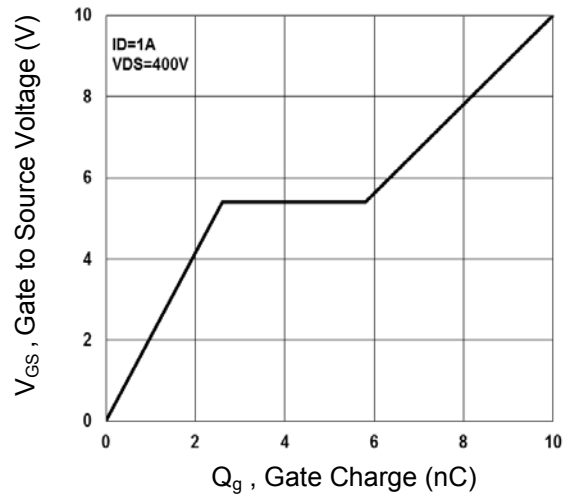
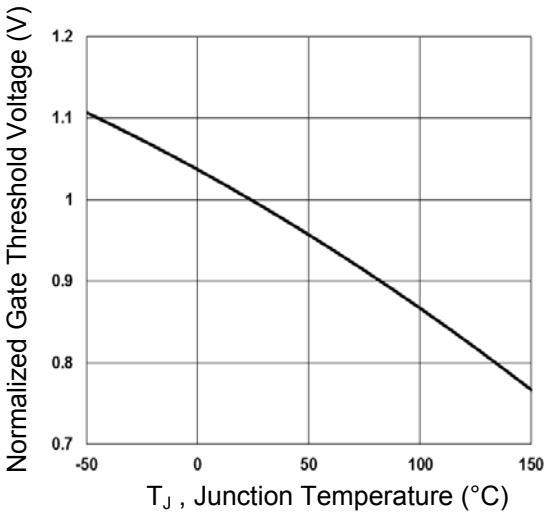
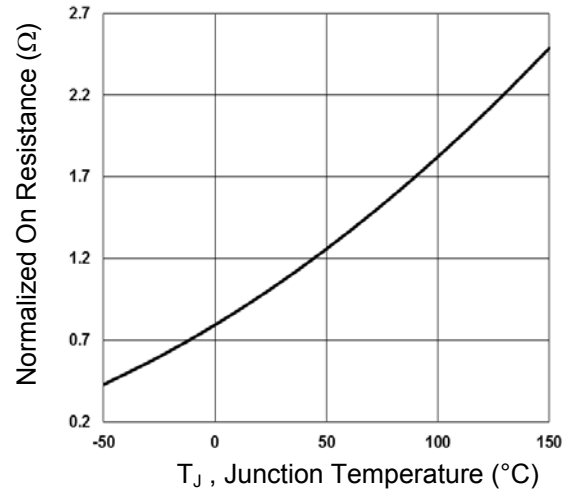
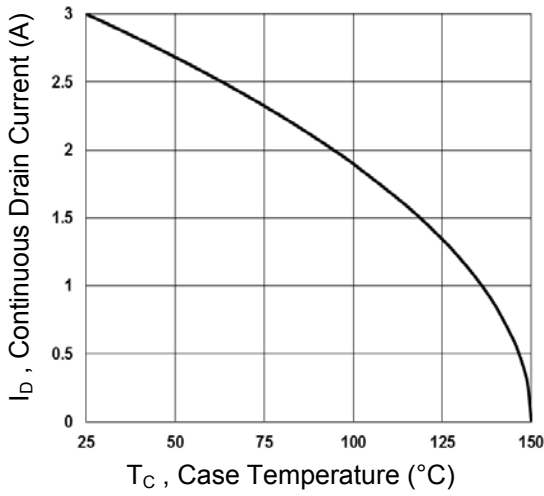
Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	500	---	---	V
BV_{DSS} Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to 25°C , $I_D=1\text{mA}$	---	0.5	---	$V/^{\circ}\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=500V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=400V, V_{GS}=0V, T_J=125^{\circ}\text{C}$	---	---	10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	± 100	nA
On characteristics						
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=1A$	---	2.6	3.6	Ω
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	3	4	5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-7	---	$\text{mV}/^{\circ}\text{C}$
Forward Transconductance	g_{fs}	$V_{DS}=10V, I_D=1A$	---	2.8	---	S
Dynamic Characteristics						
Total Gate Charge ^{3,4}	Q_g	$V_{DS}=400V, V_{GS}=10V, I_D=1A$	---	10	---	nC
Gate-Source Charge ^{3,4}	Q_{gs}		---	2.6	---	
Gate-Drain Charge ^{3,4}	Q_{gd}		---	3.2	---	
Turn-On Delay Time ^{3,4}	$T_{d(on)}$	$V_{DD}=300V, V_{GS}=10V, R_G=2.5\Omega, I_D=1A$	---	18	---	nS
Rise Time ^{3,4}	T_r		---	7	---	
Turn-Off Delay Time ^{3,4}	$T_{d(off)}$		---	23	---	
Fall Time ^{3,4}	T_f		---	16	---	
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$	---	440	---	pF
Output Capacitance	C_{oss}		---	35	---	
Reverse Transfer Capacitance	C_{rss}		---	4	---	
Gate Resistance	R_g	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	1.6	---	Ω
Drain-Source Diode Characteristics						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	$V_G=V_D=0V, \text{Force Current}$	---	---	3	A
Pulsed Source Current	I_{SM}		---	---	12	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=1A, T_J=25^{\circ}\text{C}$	---	---	1	V
Reverse Recovery Time	t_{rr}	$V_{GS}=0V, I_S=1A, di/dt=100A/\mu S, T_J=25^{\circ}\text{C}$	---	160	240	nS
Reverse Recovery Charge	Q_{rr}		---	430	650	nC

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. $V_{DD}=50V, V_{GS}=10V, L=1\text{mH}, I_{AS}=5A, R_G=25\Omega, \text{Starting } T_J=25^{\circ}\text{C}$.
3. The data tested by pulsed, pulse width $\leq 300\mu S$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves



Typical Electrical and Thermal Characteristic Curves

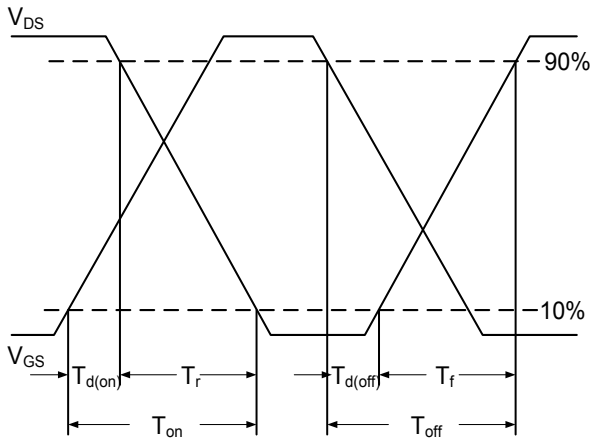


Fig.7 Switching Time Waveform

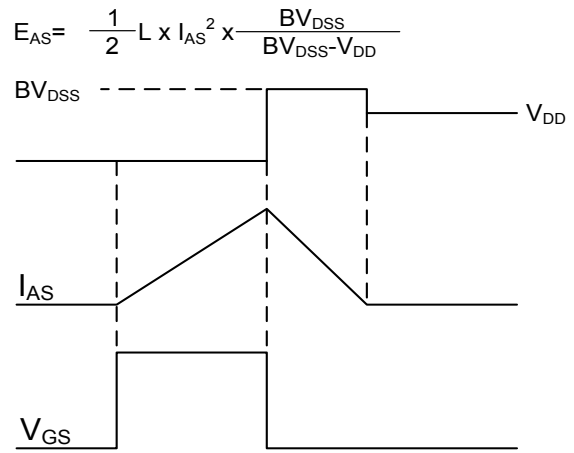
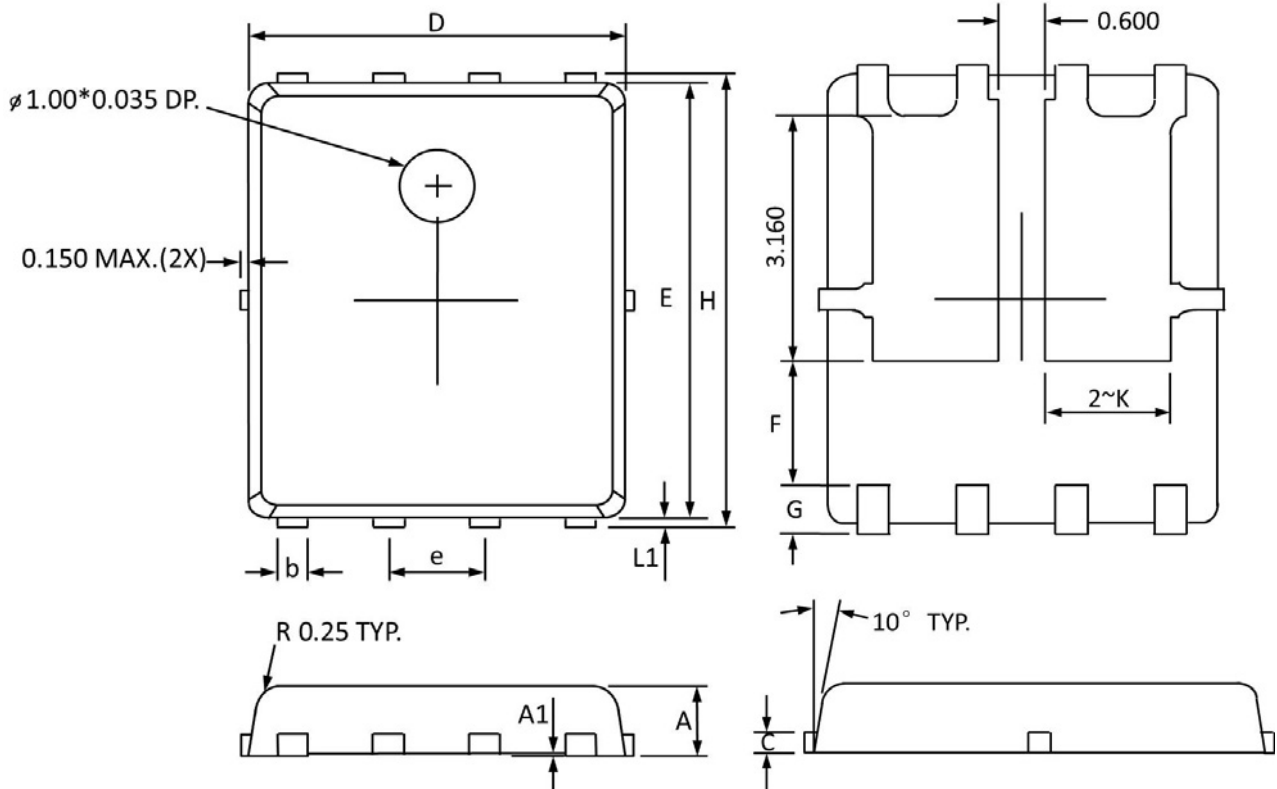


Fig.8 E_{AS} Waveform

Package Outline Dimensions PPAK5x6



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.800	1.000	0.032	0.039
A1	0.000	0.005	0.000	0.000
b	0.350	0.490	0.014	0.019
C	0.254 Ref		0.254 Ref	
D	4.900	5.100	0.193	0.200
E	5.700	5.900	0.225	0.232
e	1.27 BSC		1.27 BSC	
F	1.600 Ref		1.600 Ref	
G	0.600 Ref		0.600 Ref	
H	5.950	6.200	0.235	0.244
L1	0.100	0.180	0.004	0.007
K	1.600 Ref		1.600 Ref	